

M Z Abdullah

List of Publications by Year in descending order

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283
papers

5,112
citations

109321

35
h-index

155660

55
g-index

287
all docs

287
docs citations

287
times ranked

3109
citing authors

#	ARTICLE	IF	CITATIONS
1	Applications of porous media combustion technology – A review. <i>Applied Energy</i> , 2009, 86, 1365-1375.	10.1	266
2	Combustion in porous media and its applications – A comprehensive survey. <i>Journal of Environmental Management</i> , 2009, 90, 2287-2312.	7.8	178
3	Development and performance analysis of novel cast copper–SiC–Gr hybrid composites. <i>Materials & Design</i> , 2009, 30, 1957-1965.	5.1	175
4	Trends in modeling of porous media combustion. <i>Progress in Energy and Combustion Science</i> , 2010, 36, 627-650.	31.2	135
5	Single-phase heat transfer enhancement in micro/minichannels using nanofluids: Theory and applications. <i>Applied Energy</i> , 2016, 164, 733-755.	10.1	125
6	Analysis of biomass-residue-based cogeneration system in palm oil mills. <i>Biomass and Bioenergy</i> , 2003, 24, 117-124.	5.7	112
7	A review of investigations on liquid fuel combustion in porous inert media. <i>Progress in Energy and Combustion Science</i> , 2009, 35, 216-230.	31.2	81
8	Experiment on forced convective heat transfer enhancement using MWCNTs/GNPs hybrid nanofluid and mini-tube. <i>International Journal of Heat and Mass Transfer</i> , 2017, 115, 1121-1131.	4.8	75
9	Analysis of cold flow fluidization test results for various biomass fuels. <i>Biomass and Bioenergy</i> , 2003, 24, 487-494.	5.7	73
10	A review of combustion-driven thermoelectric (TE) and thermophotovoltaic (TPV) power systems. <i>Renewable and Sustainable Energy Reviews</i> , 2017, 71, 572-584.	16.4	66
11	Microstructure and mechanical properties of Pb-free Sn–3.0Ag–0.5Cu solder pastes added with NiO nanoparticles after reflow soldering process. <i>Materials and Design</i> , 2016, 90, 499-507.	7.0	65
12	Development of energy efficient porous medium burners on surface and submerged combustion modes. <i>Energy</i> , 2011, 36, 5132-5139.	8.8	57
13	Experimental analysis and FEM simulation of finned U-shape multi heat pipe for desktop PC cooling. <i>Energy Conversion and Management</i> , 2011, 52, 2937-2944.	9.2	57
14	Heat Transfer and Entropy Generation Abilities of MWCNTs/GNPs Hybrid Nanofluids in Microtubes. <i>Entropy</i> , 2019, 21, 480.	2.2	57
15	Effects of diamond nanoparticles reinforcement into lead-free Sn–3.0Ag–0.5Cu solder pastes on microstructure and mechanical properties after reflow soldering process. <i>Materials and Design</i> , 2015, 82, 206-215.	7.0	54
16	Piezoresistive effects in controllable defective HFTCVD graphene-based flexible pressure sensor. <i>Scientific Reports</i> , 2015, 5, 14751.	3.3	53
17	Effects of Fe ₂ NiO ₄ nanoparticles addition into lead free Sn–3.0Ag–0.5Cu solder pastes on microstructure and mechanical properties after reflow soldering process. <i>Materials & Design</i> , 2015, 67, 197-208.	5.1	51
18	Effects of the preheat layer thickness on surface/submerged flame during porous media combustion of micro burner. <i>Energy</i> , 2017, 122, 103-110.	8.8	50

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19	Thermophysical properties of Al ₂ O ₃ -CuO hybrid nanofluid at different nanoparticle mixture ratio: An experimental approach. <i>Journal of Molecular Liquids</i> , 2020, 313, 113458.	4.9	50
20	Three-dimensional numerical and experimental investigations on polymer rheology in meso-scale injection molding. <i>International Communications in Heat and Mass Transfer</i> , 2010, 37, 131-139.	5.6	48
21	Influence of nanofluid on heat transfer in a loop heat pipe. <i>International Communications in Heat and Mass Transfer</i> , 2013, 47, 82-91.	5.6	48
22	Thermo-mechanical challenges of reflowed lead-free solder joints in surface mount components: a review. <i>Soldering and Surface Mount Technology</i> , 2016, 28, 41-62.	1.5	47
23	Numerical and experimental investigations on effect of fan height on the performance of piezoelectric fan in microelectronic cooling. <i>International Communications in Heat and Mass Transfer</i> , 2009, 36, 51-58.	5.6	46
24	Application of porous medium burner with micro cogeneration system. <i>Energy</i> , 2013, 50, 131-142.	8.8	45
25	Thermal analysis of dual piezoelectric fans for cooling multi-LED packages. <i>Microelectronics Reliability</i> , 2014, 54, 1534-1543.	1.7	44
26	CFD modeling of pin shape effects on capillary flow during wave soldering. <i>International Journal of Heat and Mass Transfer</i> , 2014, 72, 400-410.	4.8	44
27	Experimental and numerical investigation of 3D gas flow temperature field in infrared heating reflow oven with circulating fan. <i>International Journal of Heat and Mass Transfer</i> , 2015, 87, 49-58.	4.8	43
28	Metal oxide nanofluids in electronic cooling: a review. <i>Journal of Materials Science: Materials in Electronics</i> , 2020, 31, 4381-4398.	2.2	43
29	Computational and experimental investigations in a cyclone dust separator. <i>Proceedings of the Institution of Mechanical Engineers, Part E: Journal of Process Mechanical Engineering</i> , 1997, 211, 247-257.	2.5	42
30	FVM based numerical study on the effect of solder bump arrangement on capillary driven flip chip underfill process. <i>International Communications in Heat and Mass Transfer</i> , 2010, 37, 281-286.	5.6	42
31	Computational fluid dynamic and thermal analysis for BGA assembly during forced convection reflow soldering process. <i>Soldering and Surface Mount Technology</i> , 2012, 24, 77-91.	1.5	42
32	Title is missing!. <i>Journal of Medical and Biological Engineering</i> , 2012, 32, 77.	1.8	42
33	Optimum tip gap and orientation of multi-piezofan for heat transfer enhancement of finned heat sink in microelectronic cooling. <i>International Journal of Heat and Mass Transfer</i> , 2012, 55, 5514-5525.	4.8	41
34	Fabrication and study on tribological characteristics of cast copper-TiO ₂ -boric acid hybrid composites. <i>Materials & Design</i> , 2009, 30, 1632-1637.	5.1	38
35	Influence of pin offset in PCB through-hole during wave soldering process: CFD modeling approach. <i>International Communications in Heat and Mass Transfer</i> , 2013, 48, 116-123.	5.6	38
36	COLOR VISION SYSTEM FOR RIPENESS INSPECTION OF OIL PALM ELAEIS GUINEENSIS. <i>Journal of Food Processing and Preservation</i> , 2002, 26, 213-235.	2.0	37

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37	Title is missing!. Journal of Medical and Biological Engineering, 2011, 31, 201.	1.8	37
38	Optimization modeling of the cooling stage of reflow soldering process for ball grid array package using the gray-based Taguchi method. Microelectronics Reliability, 2012, 52, 1143-1152.	1.7	37
39	Optimization of the reflow soldering process with multiple quality characteristics in ball grid array packaging by using the grey-based Taguchi method. Microelectronics International, 2013, 30, 151-168.	0.6	37
40	Die attachment, wire bonding, and encapsulation process in LED packaging: A review. Sensors and Actuators A: Physical, 2021, 329, 112817.	4.1	37
41	Effect of piezoelectric fan mode shape on the heat transfer characteristics. International Communications in Heat and Mass Transfer, 2014, 52, 140-151.	5.6	36
42	Optimization of IC encapsulation considering fluid/structure interaction using response surface methodology. Simulation Modelling Practice and Theory, 2012, 29, 109-122.	3.8	35
43	Fluid-structure interaction analysis on the effect of chip stacking in a 3D integrated circuit package with through-silicon vias during plastic encapsulation. Microelectronic Engineering, 2014, 113, 40-49.	2.4	35
44	Finite volume based CFD simulation of pressurized flip-chip underfill encapsulation process. Microelectronics Reliability, 2010, 50, 98-105.	1.7	34
45	Investigation of the fluid/structure interaction phenomenon in IC packaging. Microelectronics Reliability, 2012, 52, 241-252.	1.7	33
46	Feasibility study of cogeneration in a plywood industry with power export to grid. Applied Energy, 2009, 86, 657-662.	10.1	32
47	Study on the fluid/structure interaction at different inlet pressures in molded packaging. Microelectronic Engineering, 2011, 88, 3182-3194.	2.4	32
48	Fluid/Structure Interaction Analysis of the Effects of Solder Bump Shapes and Input/Output Counts on Moulded Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 604-616.	2.5	32
49	Effect of synchronized piezoelectric fans on microelectronic cooling performance. International Communications in Heat and Mass Transfer, 2013, 43, 81-89.	5.6	32
50	Influence of solder bump arrangements on molded IC encapsulation. Microelectronics Reliability, 2014, 54, 796-807.	1.7	32
51	Fluid/Structure Interaction Investigation in PBGA Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 1786-1795.	2.5	31
52	Effect of stacking chips and inlet positions on void formation in the encapsulation of 3D stacked flip-chip package. International Communications in Heat and Mass Transfer, 2012, 39, 670-680.	5.6	31
53	Effects of tip gap and amplitude of piezoelectric fans on the performance of heat sinks in microelectronic cooling. Heat and Mass Transfer, 2012, 48, 893-901.	2.1	31
54	Heat transfer enhancement of LEDs with a combination of piezoelectric fans and a heat sink. Microelectronics Reliability, 2017, 68, 39-50.	1.7	31

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55	A Brief Survey of Preparation and Heat Transfer Enhancement of Hybrid Nanofluids. Strojnikski Vestnik/Journal of Mechanical Engineering, 2019, , 441-453.	1.1	31
56	Numerical analysis on the effects of different inlet gates and gap heights in TQFP encapsulation process. International Journal of Heat and Mass Transfer, 2011, 54, 1861-1870.	4.8	30
57	Analysis of encapsulation process in 3D stacked chips with different microbump array. International Communications in Heat and Mass Transfer, 2012, 39, 1616-1623.	5.6	30
58	Application of flexible printed circuit board (FPCB) in personal computer motherboards: Focusing on mechanical performance. Microelectronics Reliability, 2012, 52, 744-756.	1.7	30
59	Three-dimensional thermal investigations at board level in a reflow oven using thermal coupling method. Soldering and Surface Mount Technology, 2012, 24, 167-182.	1.5	29
60	Lattice Boltzmann method study of bga bump arrangements on void formation. Microelectronics Reliability, 2016, 56, 170-181.	1.7	29
61	Hardness profiles of Sn-3.0Ag-0.5Cu-TiO ₂ composite solder by nanoindentation. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2016, 669, 178-186.	5.6	28
62	Numerical Analysis of Nozzle Flow and Spray Characteristics from Different Nozzles Using Diesel and Biofuel Blends. Energies, 2019, 12, 281.	3.1	28
63	Characterization of working fluid in vertically mounted finned U-shape twin heat pipe for electronic cooling. Energy Conversion and Management, 2012, 62, 31-39.	9.2	27
64	Numerical simulation of self-alignment of chip resistor components for different silver content during reflow soldering. Microelectronics Reliability, 2017, 79, 69-78.	1.7	27
65	Effect of vertical stacking dies on flow behavior of epoxy molding compound during encapsulation of stacked-chip scale packages. Heat and Mass Transfer, 2010, 46, 1315-1325.	2.1	26
66	Analysis of fluid/structure interaction: Influence of silicon chip thickness in moulded packaging. Microelectronics Reliability, 2013, 53, 334-347.	1.7	26
67	Effect of ILU dispensing types for different solder bump arrangements on CUF encapsulation process. Microelectronic Engineering, 2016, 163, 83-97.	2.4	26
68	Effect of solder bump shapes on underfill flow in flip-chip encapsulation using analytical, numerical and PIV experimental approaches. Microelectronics Reliability, 2018, 81, 41-63.	1.7	26
69	A Study on the Effect of Epoxy Molding Compound (EMC) Rheology During Encapsulation of Stacked-CHIP Scale Packages (S-CSP). Journal of Reinforced Plastics and Composites, 2009, 28, 2527-2538.	3.1	25
70	Thermal Fluid-Structure Interaction in the Effects of Pin-Through-Hole Diameter during Wave Soldering. Advances in Mechanical Engineering, 2014, 6, 275735.	1.6	25
71	Discrete phase method study of ball grid array underfill process using nano-silica filler-reinforced composite-encapsulant with varying filler loadings. Microelectronics Reliability, 2017, 72, 45-64.	1.7	25
72	Numerical Study of Heat Transfer Enhancement Using Al ₂ O ₃ -Graphene/Water Hybrid Nanofluid Flow in Mini Tubes. Iranian Journal of Science and Technology, Transaction A: Science, 2019, 43, 1989-2000.	1.5	25

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73	Design Optimization of Solid Rocket Propulsion: A Survey of Recent Advancements. <i>Journal of Spacecraft and Rockets</i> , 2020, 57, 3-11.	1.9	25
74	A CFD-based experimental analysis on the effect of free stream cooling on the performance of micro processor heat sinks. <i>International Communications in Heat and Mass Transfer</i> , 2008, 35, 771-778.	5.6	23
75	Experimental and Numerical Studies of Finned L-Shape Heat Pipe for Notebook-PC Cooling. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2013, 3, 978-988.	2.5	23
76	Study of flow visualization in stacked-Chip Scale Packages (S-CSP). <i>International Communications in Heat and Mass Transfer</i> , 2007, 34, 820-828.	5.6	22
77	Optimization of flexible printed circuit board electronics in the flow environment using response surface methodology. <i>Microelectronics Reliability</i> , 2013, 53, 1996-2004.	1.7	22
78	Effect of thermocapillary action in the underfill encapsulation of multi-stack ball grid array. <i>Microelectronics Reliability</i> , 2016, 66, 143-160.	1.7	22
79	Recent Advances on Thermally Conductive Adhesive in Electronic Packaging: A Review. <i>Polymers</i> , 2021, 13, 3337.	4.5	22
80	Computational study of a new scheme for a film-cooling hole on convex surface of turbine blades. <i>International Communications in Heat and Mass Transfer</i> , 2013, 43, 90-99.	5.6	21
81	Optimization of SiO ₂ nanoparticle mass concentration and heat input on a loop heat pipe. <i>Case Studies in Thermal Engineering</i> , 2015, 6, 238-250.	5.7	21
82	Effect of ceramic coating in combustion and cogeneration performance of Al ₂ O ₃ porous medium. <i>Journal of the Energy Institute</i> , 2016, 89, 81-93.	5.3	21
83	Centrifuge and storage precipitation of TiO ₂ nanoparticles by the sol-gel method. <i>Journal of Alloys and Compounds</i> , 2015, 651, 557-564.	5.5	20
84	Airflow inside the nasal cavity: visualization using computational fluid dynamics. <i>Asian Biomedicine</i> , 2010, 4, 657-661.	0.3	20
85	Overview of the Important Factors Influencing the Performance of Eco-Friendly Brake Pads. <i>Polymers</i> , 2022, 14, 1180.	4.5	20
86	Optimization of aerodynamic efficiency for twist morphing MAV wing. <i>Chinese Journal of Aeronautics</i> , 2014, 27, 475-487.	5.3	19
87	Discrimination and classification of <i>Eurycoma longifolia</i> Jack in medicinal foods by means of a DSP-based electronic taste sensor. <i>Transactions of the Institute of Measurement and Control</i> , 2004, 26, 19-39.	1.7	18
88	Effect of Solder Joint Arrangements on BGA Lead-Free Reliability During Cooling Stage of Reflow Soldering Process. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2012, 2, 2098-2107.	2.5	18
89	Fluid Structure Interaction of Unsteady Aerodynamics of Flapping Wing at Low Reynolds Number. <i>Engineering Applications of Computational Fluid Mechanics</i> , 2013, 7, 144-158.	3.1	18
90	Effect of Side and Tip Gaps of a Piezoelectric Fan on Microelectronic Cooling. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2013, 3, 1545-1553.	2.5	18

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91	Experimental analysis of a porous burner operating on kerosene-vegetable cooking oil blends for thermophotovoltaic power generation. <i>Energy Conversion and Management</i> , 2015, 96, 544-560.	9.2	18
92	Experimental Investigation of Water-Cooled Heat Pipes in the Thermal Management of Lithium-Ion EV Batteries. <i>Arabian Journal for Science and Engineering</i> , 2019, 44, 7541-7552.	3.0	18
93	Effects of outlet vent arrangement on air traps in stacked-chip scale package encapsulation. <i>International Communications in Heat and Mass Transfer</i> , 2012, 39, 405-413.	5.6	17
94	Computational aerodynamic analysis on perimeter reinforced (PR)-compliant wing. <i>Chinese Journal of Aeronautics</i> , 2013, 26, 1093-1105.	5.3	17
95	Design of disposable DNA biosensor microchip with amperometric detection featuring PCB substrate. <i>Biochip Journal</i> , 2013, 7, 51-56.	4.9	17
96	Influence of PTH offset angle in wave soldering with thermal-coupling method. <i>Soldering and Surface Mount Technology</i> , 2014, 26, 97-109.	1.5	17
97	Numerical investigations on the effects of different cooling periods in reflow-soldering process. <i>Heat and Mass Transfer</i> , 2015, 51, 1413-1423.	2.1	17
98	Experimental investigation of the performance of a liquid fuel-fired porous burner operating on kerosene-vegetable cooking oil (VCO) blends for micro-cogeneration of thermoelectric power. <i>Renewable Energy</i> , 2015, 74, 505-516.	8.9	17
99	Study on convective heat transfer and pressure drop of MWCNTs/water nanofluid in mini-tube. <i>Journal of Thermal Analysis and Calorimetry</i> , 2019, 135, 123-132.	3.6	17
100	Optimization of pin through hole connector in thermal fluid-structure interaction analysis of wave soldering process using response surface methodology. <i>Simulation Modelling Practice and Theory</i> , 2015, 57, 45-57.	3.8	16
101	Recent fluid-structure interaction modeling challenges in IC encapsulation – A review. <i>Microelectronics Reliability</i> , 2014, 54, 1511-1526.	1.7	15
102	Lattice Boltzmann method study of effect three dimensional stacking-chip package layout on micro-void formation during encapsulation process. <i>Microelectronics Reliability</i> , 2016, 65, 205-216.	1.7	15
103	CUF scaling effect on contact angle and threshold pressure. <i>Soldering and Surface Mount Technology</i> , 2017, 29, 173-190.	1.5	15
104	Stencil printing process performance on various aperture size and optimization for lead-free solder paste. <i>International Journal of Advanced Manufacturing Technology</i> , 2019, 102, 3369-3379.	3.0	15
105	Selected water thermal properties from molecular dynamics for engineering purposes. <i>Journal of Molecular Liquids</i> , 2021, 324, 114703.	4.9	15
106	Influence of Gap Height in Flip Chip Underfill Process With Non-Newtonian Flow Between Two Parallel Plates. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2012, 134, .	1.8	14
107	Experimental Investigation and Optimization of Heat Input and Coolant Velocity of Finned Twin U-Shaped Heat Pipe for CPU Cooling. <i>Experimental Techniques</i> , 2013, 37, 34-40.	1.5	14
108	Comparative assessment of a porous burner using vegetable cooking oil-kerosene fuel blends for thermoelectric and thermophotovoltaic power generation. <i>Fuel</i> , 2016, 180, 137-147.	6.4	14

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109	Lattice Boltzmann Method of Different BGA Orientations on I-Type Dispensing Method. PLoS ONE, 2016, 11, e0159357.	2.5	14
110	3-D conjugate heat transfer analysis of PLCC packages mounted in-line on a Printed Circuit Board. International Communications in Heat and Mass Transfer, 2009, 36, 813-819.	5.6	13
111	CFD simulation and experimental analysis of flow dynamics and grinding performance of opposed fluidized bed air jet mill. International Journal of Mineral Processing, 2011, 98, 94-105.	2.6	13
112	Underfill process for two parallel plates and flip chip packaging. International Communications in Heat and Mass Transfer, 2012, 39, 1205-1212.	5.6	13
113	High-speed implementation of fractal image compression in low cost FPGA. Microprocessors and Microsystems, 2016, 47, 429-440.	2.8	13
114	Effect of Wing Deformation on the Aerodynamic Performance of Flapping Wings: Fluid-Structure Interaction Approach. Journal of Aerospace Engineering, 2016, 29, .	1.4	13
115	Finite volume-based simulation of the wave soldering process: Influence of the conveyor angle on pin-through-hole capillary flow. Numerical Heat Transfer; Part A: Applications, 2016, 69, 295-310.	2.1	13
116	Filling efficiency of flip-chip underfill encapsulation process. Soldering and Surface Mount Technology, 2019, 32, 10-18.	1.5	13
117	Thermal analysis of micro-channel heat exchangers with two-phase flow using FEM. International Journal of Numerical Methods for Heat and Fluid Flow, 2005, 15, 43-60.	2.8	12
118	Thermal fluid-structure interaction of PCB configurations during the wave soldering process. Soldering and Surface Mount Technology, 2015, 27, 31-44.	1.5	12
119	Heat Transfer in a Loop Heat Pipe using Diamond-H ₂ O Nanofluid. Heat Transfer Engineering, 2018, 39, 1117-1131.	1.9	12
120	Nanofluid-filled heat pipes in managing the temperature of EV lithium-ion batteries. Journal of Physics: Conference Series, 2019, 1349, 012123.	0.4	12
121	Investigations of Infrared Desktop Reflow Oven with FPCB Substrate during Reflow Soldering Process. Metals, 2021, 11, 1155.	2.3	12
122	Simulation Investigations on Fluid/Structure Interaction in the Reflow Soldering Process of Board-Level BGA Packaging. International Journal of Computer Theory and Engineering, 2013, , 645-649.	3.4	12
123	Early stage breast cancer detection by means of time-domain ultra-wide band sensing. Measurement Science and Technology, 2011, 22, 114016.	2.6	11
124	Study on the Fluid-Structure Interaction of Flexible Printed Circuit Board Electronics in the Flow Environment. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 1335-1345.	2.5	11
125	Characteristic Airflow Patterns During Inspiration and Expiration: Experimental and Numerical Investigation. Journal of Medical and Biological Engineering, 2015, 35, 387-394.	1.8	11
126	Fluid/structure interaction study on the variation of radial gate's gap height in dam. IOP Conference Series: Materials Science and Engineering, 2018, 370, 012063.	0.6	11

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127	Correlating scalants characteristic and air bubbling rate in submerged vacuum membrane distillation: A fouling control strategy. <i>Journal of Membrane Science</i> , 2021, 621, 118991.	8.2	11
128	Development of Flexible Wings and Flapping Mechanism with Integrated Electronic Control System, for Micro Air Vehicle Research. <i>Experimental Techniques</i> , 2013, 37, 25-37.	1.5	10
129	COMPUTATIONAL FLUID DYNAMICS STUDY OF PULL AND PLUG FLOW BOUNDARY CONDITION ON NASAL AIRFLOW. <i>Biomedical Engineering - Applications, Basis and Communications</i> , 2013, 25, 1350044.	0.6	10
130	Numerical Investigation on the Effect of Pressure and Temperature on the Melt Filling During Injection Molding Process. <i>Arabian Journal for Science and Engineering</i> , 2016, 41, 1907-1919.	1.1	10
131	Physical, mechanical, and thermal properties improvement of porous alumina substrate through dip-coating and re-sintering procedures. <i>Ceramics International</i> , 2016, 42, 7717-7729.	4.8	10
132	Experimental and numerical investigation of flow and thermal effects on flexible printed circuit board. <i>Microelectronics Reliability</i> , 2017, 72, 5-17.	1.7	10
133	Effect of scale size, orientation type and dispensing method on void formation in the CUF encapsulation of BGA. <i>Sadhana - Academy Proceedings in Engineering Sciences</i> , 2018, 43, 1.	1.3	10
134	Three-Dimensional Modelling to Study the Effect of Die-Stacking Shape on Mould Filling During Encapsulation of Microelectronic Chips. <i>IEEE Transactions on Advanced Packaging</i> , 2010, 33, 438-446.	1.6	9
135	A Mesoscale Premixed LPG Burner with Surface Combustion in Porous Ceramic Foam. <i>Energy Sources, Part A: Recovery, Utilization and Environmental Effects</i> , 2011, 34, 9-18.	2.3	9
136	Applications of Porous Media Combustion Technology. , 2014, , 615-633.		9
137	Reflow Optimization Process: Thermal Stress Using Numerical Analysis and Intermetallic Spallation in Backwards Compatibility Solder Joints. <i>Arabian Journal for Science and Engineering</i> , 2015, 40, 1669-1679.	1.1	9
138	Effect of Skin Flexibility on Aerodynamic Performance of Flexible Skin Flapping Wings for Micro Air Vehicles. <i>Experimental Techniques</i> , 2015, 39, 11-20.	1.5	9
139	Discrete phase method particle simulation of ultra-fine package assembly with SAC305-TiO ₂ nano-reinforced lead free solder at different weighted percentages. <i>Microelectronics Reliability</i> , 2017, 79, 336-351.	1.7	9
140	Investigation on nano-reinforced solder paste after reflow soldering part 1: Effects of nano-reinforced solder paste on melting, hardness, spreading rate, and wetting quality. <i>Microelectronics Reliability</i> , 2018, 84, 230-237.	1.7	9
141	Assessment of porous media combustion with foam porous media for surface/submerged flame. <i>Materials Today: Proceedings</i> , 2018, 5, 20865-20873.	1.8	9
142	Plastic Ball Grid Array Encapsulation Process Simulation on Rheology Effect. <i>Telkomnika (Telecommunication Computing Electronics and Control)</i> , 2011, 9, 27.	0.8	9
143	Effects of Blade Number on the Centrifugal Pump Performance: A Review. <i>Arabian Journal for Science and Engineering</i> , 2022, 47, 7945-7961.	3.0	9
144	Conjugate film cooling of a new multi-layer convex surface of turbine blades. <i>International Communications in Heat and Mass Transfer</i> , 2013, 45, 86-94.	5.6	8

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145	Lattice Boltzmann Model of 3D Multiphase Flow in Artery Bifurcation Aneurysm Problem. Computational and Mathematical Methods in Medicine, 2016, 2016, 1-17.	1.3	8
146	Influence of Material Properties on the Fluid-Structure Interaction aspects during Molded Underfill Process. MATEC Web of Conferences, 2017, 97, 01059.	0.2	8
147	High-Speed Fractal Image Compression Featuring Deep Data Pipelining Strategy. IEEE Access, 2018, 6, 71389-71403.	4.2	8
148	A practical approach in porous medium combustion for domestic application: A review. IOP Conference Series: Materials Science and Engineering, 2018, 370, 012004.	0.6	8
149	Numerical study on the influence of nozzle spray shape on spray characteristics using diesel and biofuel blends. Biofuels, 2021, 12, 1109-1121.	2.4	8
150	Comparative Study of Pressurized and Capillary Underfill Flow Using Lattice Boltzmann Method. Arabian Journal for Science and Engineering, 2019, 44, 7627-7652.	3.0	8
151	The Effect of Sintering Conditions on the Microstructure and Electrical Properties of Pb(Zr _{0.52} Ti _{0.48})O ₃ Ceramic. Journal of Mechanical Engineering and Sciences, 2014, 6, 901-906.	0.6	8
152	DEVELOPMENT OF PREMIXED BURNER BASED ON STABILIZED COMBUSTION WITHIN DISCRETE POROUS MEDIUM. Journal of Porous Media, 2011, 14, 909-917.	1.9	8
153	Husk-Fueled Steam Turbine Cogeneration for a Rice Mill with Power Export—A Case Study. Energy Sources, Part A: Recovery, Utilization and Environmental Effects, 2011, 33, 724-734.	2.3	7
154	The Development and Performance Analysis of Partially Premixed LPG Porous Medium Combustor. Energy Sources, Part A: Recovery, Utilization and Environmental Effects, 2011, 33, 1260-1270.	2.3	7
155	Flow Induced Deflection and Stress on Flexible Printed Circuit Board in Fan-Cooled Electronic Systems: FSI Approach. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 617-624.	2.5	7
156	Computational prediction into staggered film cooling holes on convex surface of turbine blade. International Communications in Heat and Mass Transfer, 2012, 39, 1367-1374.	5.6	7
157	Detection of Cracks in Concrete Structure Using Microwave Imaging Technique. International Journal of Microwave Science and Technology, 2016, 2016, 1-6.	0.6	7
158	Heat transfer enhancement by flexible printed circuit board's deformation. International Communications in Heat and Mass Transfer, 2017, 84, 86-93.	5.6	7
159	Optimization of 3D IC stacking chip on molded encapsulation process: a response surface methodology approach. International Journal of Advanced Manufacturing Technology, 2019, 103, 1139-1153.	3.0	7
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